

Rajeev Joshi
Application No.: 09/730,932
Page 2

PATENT

- a' cont.*
- 4 b. a first die coupled to a first side of the base with solder;
5 c. a second die coupled to a second side of the base with solder; and
6 d. a molded body surrounding at least a portion of the leadframe and
7 the dies.
-

Please cancel claim 7 and 8.

REMARKS

Claims 1-6 are pending.

Claims 1-4 stand rejected under 35 USC §102(e) as being clearly anticipated by Pu.

Claims 3-6 stand rejected under 35 USC §103(a) as being unpatentable over Pu et al. in view of Tagawa et al. and Choi et al.

These rejections are respectfully traversed and reconsideration is respectfully requested.

Applicant has amended claim 1 to make it clear that the lead frame includes a base and has a plurality of legs extending therefrom. This can clearly be seen in figure 1 of the present application. The first die is coupled to a first side of the base with solder while a second die is coupled to a second side of the base with solder.

It is respectfully submitted that Pu et al. disclose a plurality of leads, with each lead being individually coupled to each die. The leads are not extending from a common base. Accordingly, it is respectfully submitted that Pu et al. do not anticipate claim 1 and therefore, claim 1 is allowable.

Claims 2-6 depend, either directly or indirectly on claim 1 and therefore, they are allowable for at least the reasons for at least the reasons claim 1 is allowable.

Rajeev Joshi
Application No.: 09/730,932
Page 3

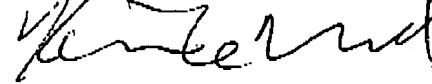
PATENT

CONCLUSION

In view of the foregoing, Applicants believe all claims now pending in this Application are in condition for allowance. The issuance of a formal Notice of Allowance at an early date is respectfully requested.

If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at .

Respectfully submitted,



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Rajeev Joshi
Application No.: 09/730,932
Page 4

PATENT

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

- 1 1. (Amended) A chip device comprising:
- 2 a. a leadframe comprising a base and a plurality of leads extending
- 3 therefrom;
- 4 b. a first die coupled to a first side of the [leadframe] base with solder;
- 5 c. a second die coupled to a second side of the [leadframe] base with
- 6 solder; and
- 7 d. a molded body surrounding at least a portion of the leadframe and the
- 8 dies.

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